



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

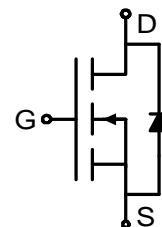
N-CHANNEL ENHANCEMENT MODE POWER MOSFET

SGT MOS、低内阻、低结电容开关损耗小

TF5N10

Description

The TF5N10 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

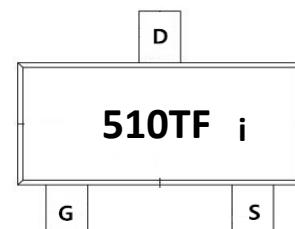


General Features

$V_{DS} = 100V$ $I_D = 5A$

$R_{DS(ON\ typ)} = 90m\Omega$ @ $V_{GS}=10V$

$R_{DS(ON\ typ)} = 115m\Omega$ @ $V_{GS}=4.5V$

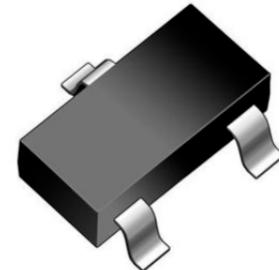


Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TF5N10	SOT-23	510TF	3000

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	5	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	3.2	A
I_{DM}	Pulsed Drain Current ²	15	A
$P_D@T_A=25^\circ C$	Total Power Dissipation ³	3.1	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-ambient(steady state) ¹	100	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction-ambient($t < 10s$) ¹	40	$^\circ C/W$



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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$	100	108	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=4\text{A}$	---	90	125	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=2\text{A}$	---	115	145	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=250\mu\text{A}$	1.2	1.7	2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=85^\circ\text{C}$	---	---	50	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2.3	4.6	
Q_g	Total Gate Charge (10V)	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=4\text{A}$	---	3.57	---	nC
Q_{gs}	Gate-Source Charge		---	0.76	---	
Q_{gd}	Gate-Drain Charge		---	0.71	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_g=3.3$ $I_{\text{D}}=1\text{A}$	---	11	---	ns
T_r	Rise Time		---	6	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	30	---	
T_f	Fall Time		---	4	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	182	---	pF
C_{oss}	Output Capacitance		---	30	---	
C_{rss}	Reverse Transfer Capacitance		---	3.6	---	
I_s	Continuous Source Current ^{1,4}	$V_G=V_D=0\text{V}$, Force Current	---	---	2	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

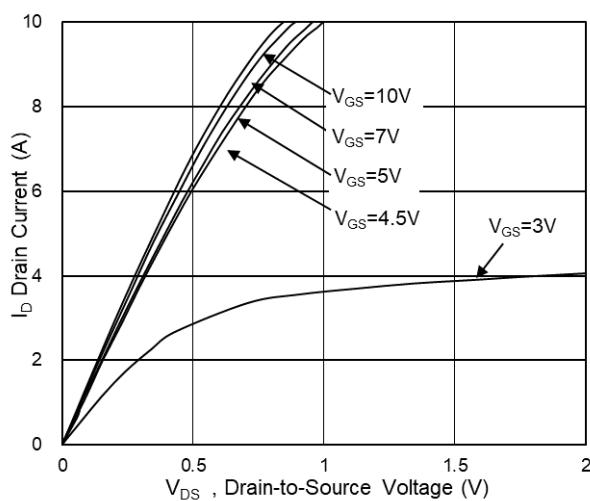


Fig.1 Typical Output Characteristics

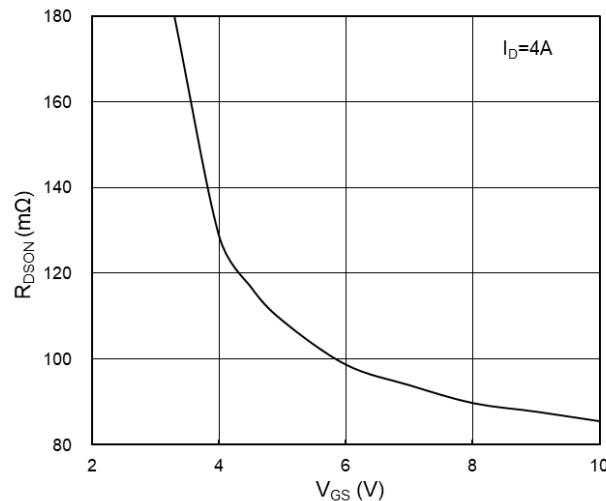


Fig.2 On-Resistance vs G-S Voltage

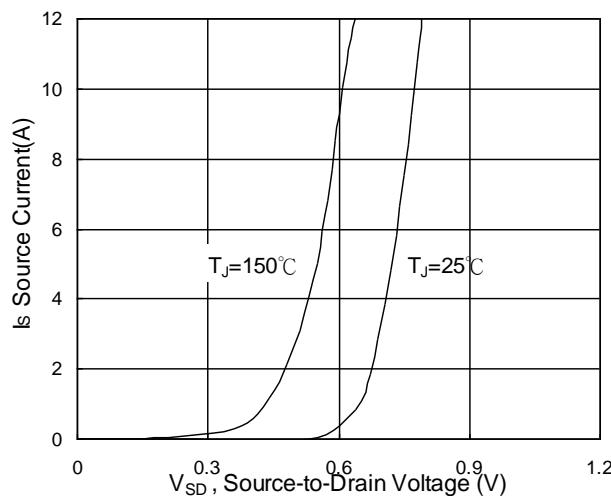


Fig.3 Source Drain Forward Characteristics

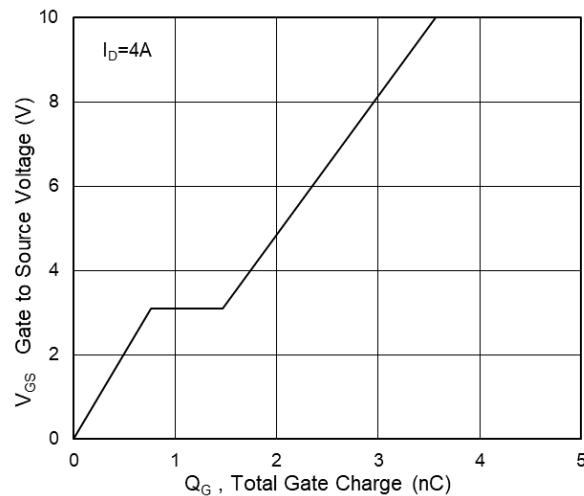


Fig.4 Gate-Charge Characteristics

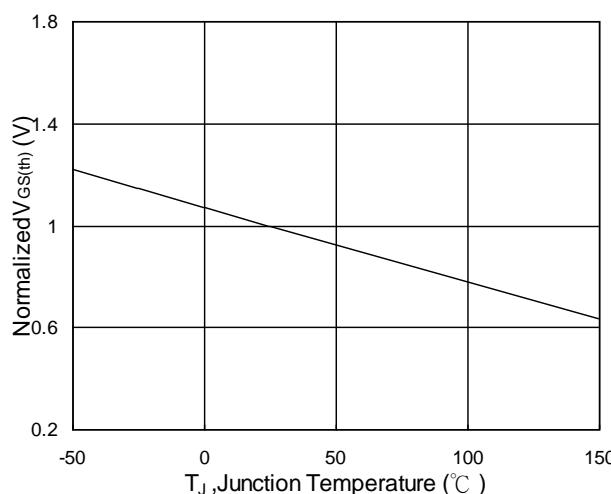


Fig.5 Normalized $V_{GS(th)}$ vs T_J

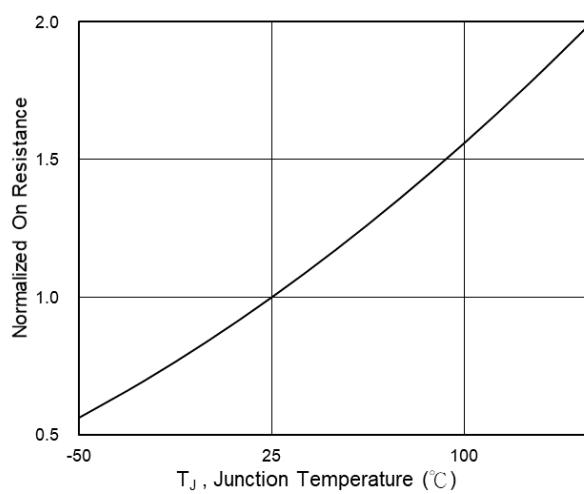


Fig.6 Normalized $R_{DS(on)}$ vs T_J

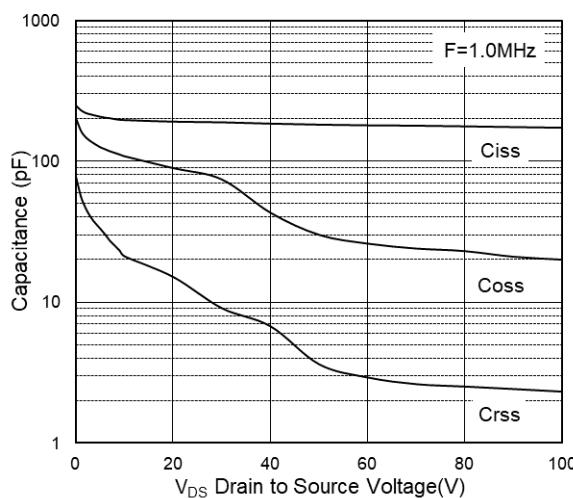


Fig.7 Capacitance

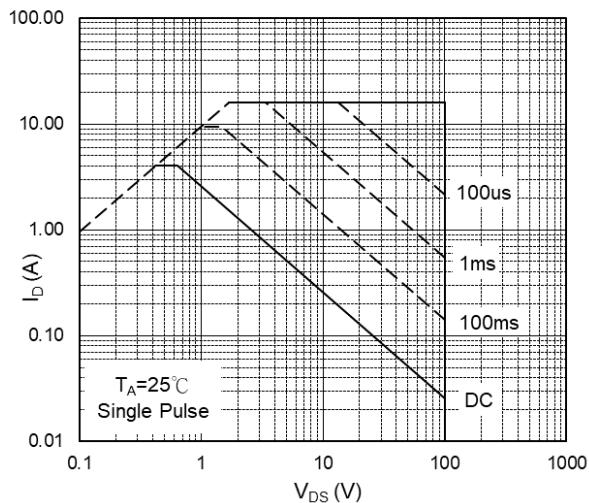


Fig.8 Safe Operating Area

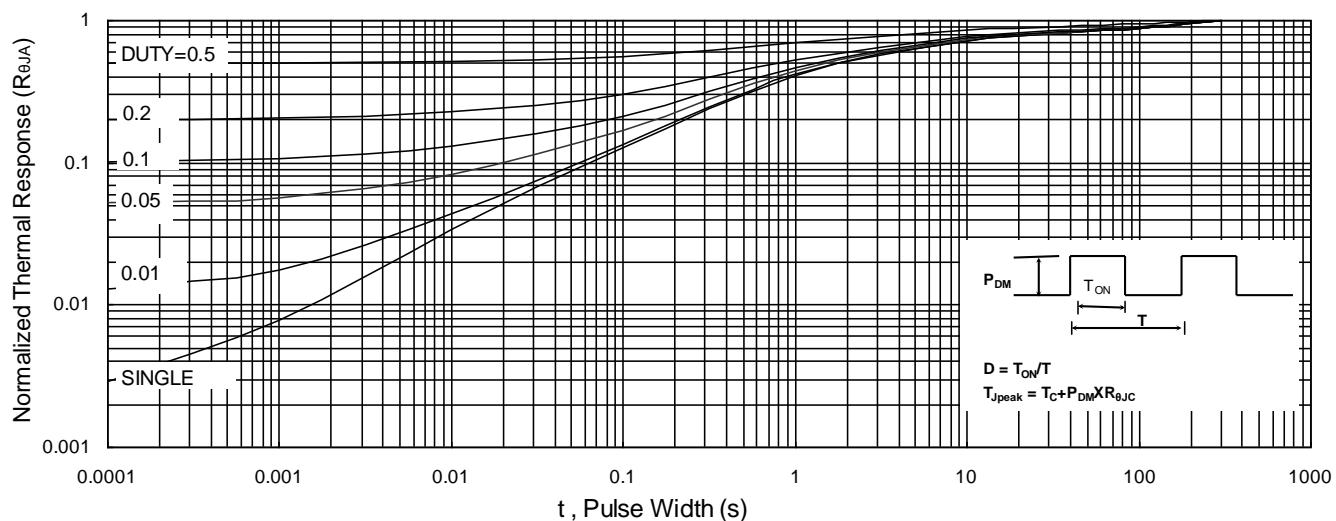


Fig.9 Normalized Maximum Transient Thermal Impedance

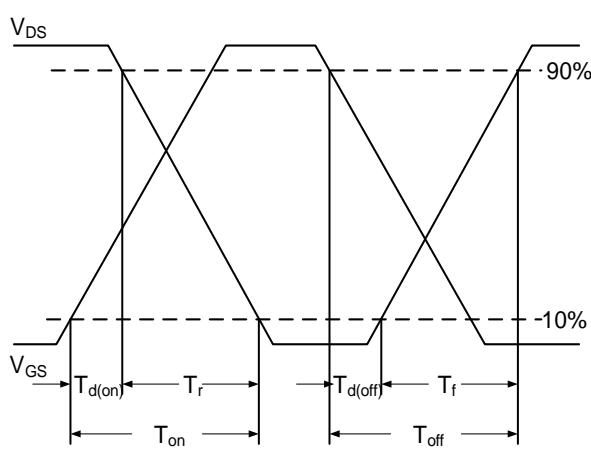


Fig.10 Switching Time Waveform

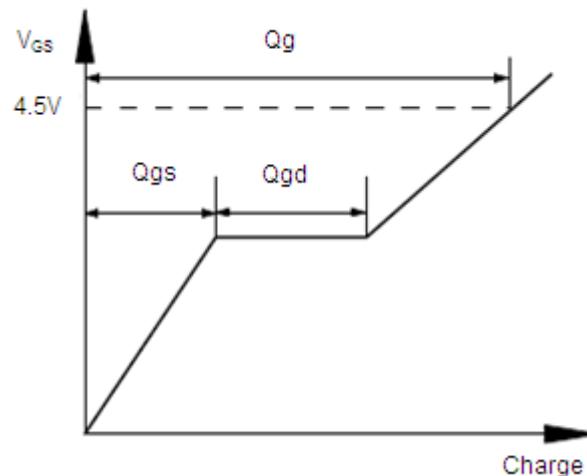


Fig.11 Gate Charge Waveform



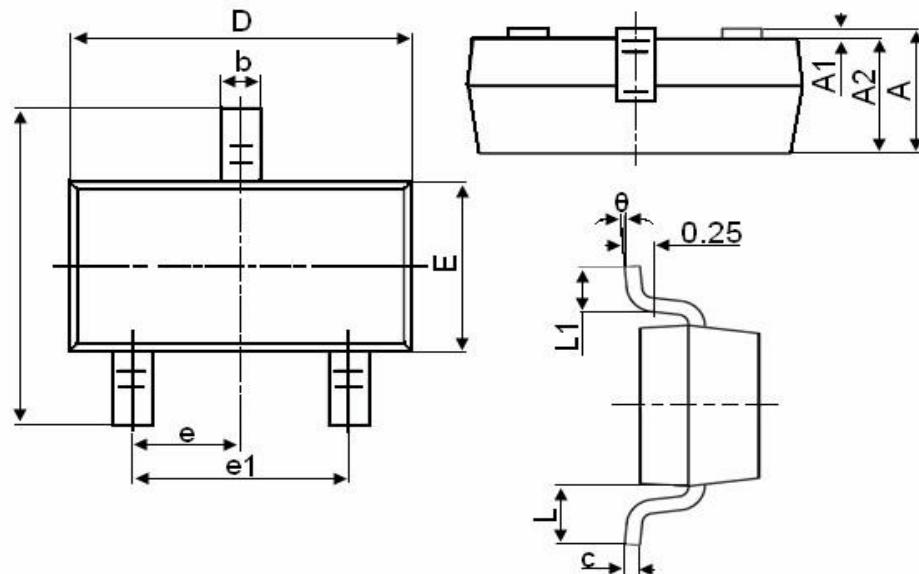
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Package Mechanical Data-SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°